

Micropower quad CMOS voltage comparators

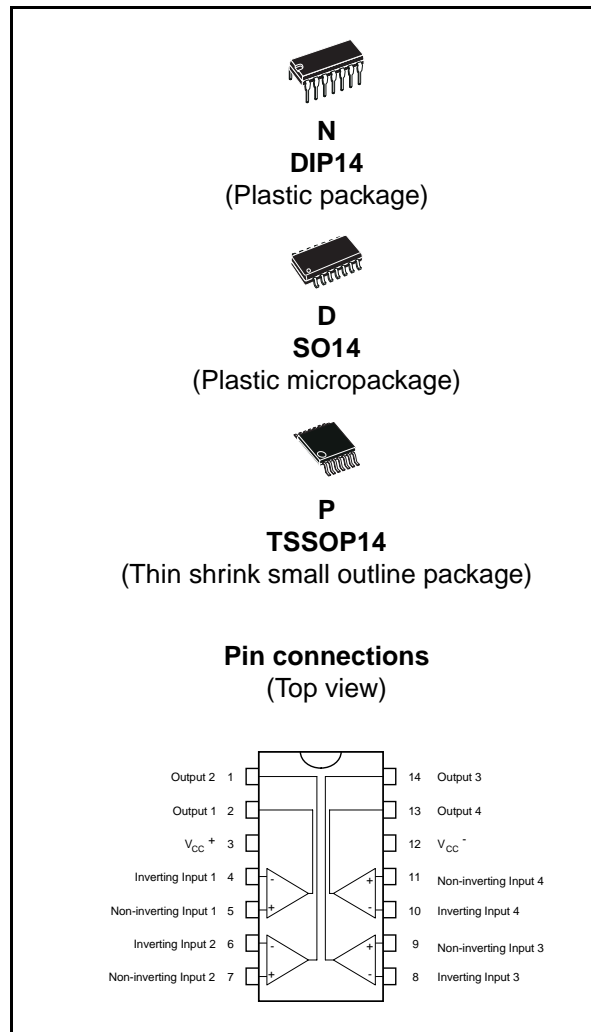
Features

- Push-pull CMOS output (no external pull-up resistor required)
- Extremely low supply current: 9µA typ per comparator
- Wide single supply range 2.7V to 16V or dual supplies (±1.35V to ±8V)
- Extremely low input bias current: 1pA typ
- Extremely low input offset current: 1pA typ
- Input common-mode voltage range includes GND
- High input impedance: $10^{12}\Omega$ typ
- Last response time: 2µs typ. for 5mV overdrive
- Pin-to-pin and functionally compatible with bipolar LM339

Description

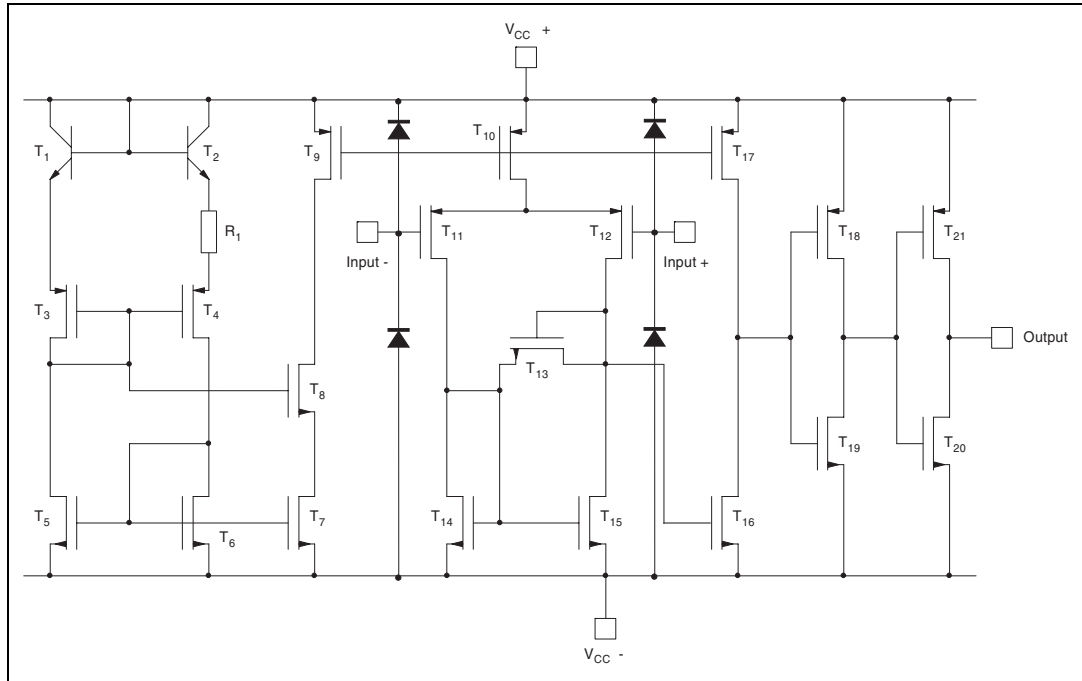
The TS3704 is a micropower CMOS quad voltage comparator with extremely low consumption of 9µA typ / comparator (20 times less than bipolar LM339). The push-pull CMOS output stage allows power and space saving by eliminating the external pull-up resistor required by usual open-collector output comparators.

Thus response times remain similar to the LM339.



1 Schematic diagram

Figure 1. Schematic diagram (for 1/4 TS3704)



2 Absolute maximum ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}^+	Supply voltage ⁽¹⁾	18	V
V_{id}	Differential input voltage ⁽²⁾	± 18	V
V_i	Input voltage ⁽³⁾	18	V
V_o	Output voltage	18	V
I_o	Output current	20	mA
I_F	Forward current in ESD protection diodes on input ⁽⁴⁾	50	mA
P_d	Power dissipation ⁽⁵⁾		
	DIP14	1500	mW
	SO14	830	
TSSOP14	710		
T_{stg}	Storage temperature range	-65 to +150	°C
ESD	HBM: human body model ⁽⁶⁾	500	V
	MM: machine model ⁽⁷⁾	50	V
	CDM: charged device model ⁽⁸⁾	1.5	kV

- All voltage values, except differential voltage, are with respect to network ground terminal.
- Differential voltages are the non-inverting input terminal with respect to the inverting input terminal.
- The magnitude of the input and the output voltages must never exceed the magnitude of the positive and negative supply voltages.
- Guaranteed by design.
- P_d is calculated with $T_{amb} = +25^\circ\text{C}$, $T_j = +150^\circ\text{C}$ and
 $R_{thja} = 80^\circ\text{C/W}$ for DIP14 package
 $R_{thja} = 150^\circ\text{C/W}$ for SO14 package
 $R_{thja} = 175^\circ\text{C/W}$ for TSSOP14 package
- Human body model: A 100pF capacitor is charged to the specified voltage, then discharged through a 1.5k Ω resistor between two pins of the device. This is done for all couples of connected pin combinations while the other pins are floating.
- Machine model: A 200pF capacitor is charged to the specified voltage, then discharged directly between two pins of the device with no external series resistor (internal resistor < 5 Ω). This is done for all couples of connected pin combinations while the other pins are floating.
- Charged device model: all pins and the package are charged together to the specified voltage and then discharged directly to the ground through only one pin. This is done for all pins.

Table 2. Operating conditions

Symbol	Parameter	Value	Unit
V_{CC}^+	Supply voltage TS3704C, TS3704I TS3704M	2.7 to 16 4 to 16	V
V_{icm}	Common mode input voltage range	0 to $V_{CC}^+ - 1.5$	V
T_{oper}	Operating free-air temperature range TS3704C TS3704I TS3704M	0 to +70 -40 to +125 -55 to +125	°C

3 Electrical characteristics

Table 3. $V_{CC}^+ = 3V$, $V_{CC}^- = 0V$, $T_{amb} = 25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{io}	Input offset voltage ⁽¹⁾ $V_{ic} = 1.5V$ $T_{min} \leq T_{amb} \leq T_{max}$			5 6.5	mV
I_{io}	Input offset current ⁽²⁾ $V_{ic} = 1.5V$ $T_{min} \leq T_{amb} \leq T_{max}$		1	300	pA
I_{ib}	Input bias current ⁽²⁾ $V_{ic} = 1.5V$ $T_{min} \leq T_{amb} \leq T_{max}$		1	600	pA
V_{icm}	Input common mode voltage range $T_{min} \leq T_{amb} \leq T_{max}$	0 0		$V_{CC}^+ - 1.2$ $V_{CC}^+ - 1.5$	V
CMR	Common-mode rejection ratio $V_{ic} = V_{icm\ min}$		80		dB
SVR	Supply voltage rejection ratio $V_{CC}^+ = 3V$ to $5V$		75		dB
V_{OH}	High level output voltage $V_{id} = 1V$, $I_{OH} = -4mA$ $T_{min} \leq T_{amb} \leq T_{max}$	2 1.8	2.4		V
V_{OL}	Low level output voltage $V_{id} = -1V$, $I_{OL} = 4mA$ $T_{min} \leq T_{amb} \leq T_{max}$		300	400 575	mV
I_{CC}	Supply current (each comparator) No load - Outputs low $T_{min} \leq T_{amb} \leq T_{max}$		7	20 25	μA
t_{PLH}	Response time low to high $V_{ic} = 0V$, $f = 10kHz$, $C_L = 50pF$, overdrive = 5mV TTL input		1.2 0.7		μs
t_{PHL}	Response time high to low $V_{ic} = 0V$, $f = 10kHz$, $C_L = 50pF$, overdrive = 5mV TTL input		2 0.15		μs

1. The specified offset voltage is the maximum value required to drive the output up to 2.5V or down to 0.3V.
2. Maximum values include unavoidable inaccuracies of the industrial tests.

Table 4. $V_{CC}^+ = 5V$, $V_{CC}^- = 0V$, $T_{amb} = 25^\circ C$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{io}	Input offset voltage ⁽¹⁾ $V_{ic} = 2.5V$, $V_{CC}^+ = 5V$ to $10V$ $T_{min} \leq T_{amb} \leq T_{max}$		1.2	5 6.5	mV
I_{io}	Input offset current ⁽²⁾ $V_{ic} = 2.5V$ $T_{min} \leq T_{amb} \leq T_{max}$		1	300	pA
I_{ib}	Input bias current ⁽²⁾ $V_{ic} = 2.5V$ $T_{min} \leq T_{amb} \leq T_{max}$		1	600	pA
V_{icm}	Input common mode voltage range $T_{min} \leq T_{amb} \leq T_{max}$	0 0		$V_{CC}^+ - 1.2$ $V_{CC}^+ - 1.5$	V
CMR	Common-mode rejection ratio $V_{ic} = V_{icm \text{ min}}$		80		dB
SVR	Supply voltage rejection ratio $V_{CC}^+ = +5V$ to $+10V$		92		dB
V_{OH}	High level output voltage $V_{id} = 1V$, $I_{OH} = -4mA$ $T_{min} \leq T_{amb} \leq T_{max}$	4.5 4.3	4.7		V
V_{OL}	Low level output voltage $V_{id} = -1V$, $I_{OL} = 4mA$ $T_{min} \leq T_{amb} \leq T_{max}$		200	300 375	mV
I_{CC}	Supply current (each comparator) No load - Outputs low		9	20 25	μA
t_{PLH}	Response time low to high $V_{ic} = 0V$, $f = 10kHz$, $C_L = 50pF$, overdrive = 5mV Overdrive = 10mV Overdrive = 20mV Overdrive = 40mV TTL input		1.2 1 0.9 0.8 0.7		μs
t_{PHL}	Response time high to low $V_{ic} = 0V$, $f = 10kHz$, $C_L = 50pF$, overdrive = 5mV Overdrive = 10mV Overdrive = 20mV Overdrive = 40mV TTL input		2 1.5 0.9 0.7 0.15		μs
t_f	Fall time $f = 10kHz$, $C_L = 50pF$, overdrive 50mV		30		ns

1. The specified offset voltage is the maximum value required to drive the output up to 4.5V or down to 0.3V.
2. Maximum values include unavoidable inaccuracies of the industrial tests.

4 Package information

In order to meet environmental requirements, STMicroelectronics offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an STMicroelectronics trademark. ECOPACK specifications are available at: www.st.com.

4.1 DIP14 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
a1	0.51			0.020		
B	1.39		1.65	0.055		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		15.24			0.600	
F			7.1			0.280
l			5.1			0.201
L		3.3			0.130	
Z	1.27		2.54	0.050		0.100

The figure contains three mechanical drawings of the DIP14 package. The top drawing is a perspective view showing the package body and pins. Dimensions labeled include: a1 (pin height), B (pin pitch), b (pin width), b1 (pin thickness), e (pin spacing), e3 (total pin length), F (package height), l (package length), and Z (lead length). The middle drawing is a side view showing the package width E and the pin thickness b1. The bottom drawing is a top-down view showing the package length D and height F, with pin numbers 1, 7, 8, and 14 indicated.

4.2 SO14 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.75			0.068
a1	0.1		0.2	0.003		0.007
a2			1.65			0.064
b	0.35		0.46	0.013		0.018
b1	0.19		0.25	0.007		0.010
C		0.5			0.019	
c1	45° (typ.)					
D	8.55		8.75	0.336		0.344
E	5.8		6.2	0.228		0.244
e		1.27			0.050	
e3		7.62			0.300	
F	3.8		4.0	0.149		0.157
G	4.6		5.3	0.181		0.208
L	0.5		1.27	0.019		0.050
M			0.68			0.026
S	8° (max.)					
<p>The image contains three mechanical drawings of the SO14 package. The top-left drawing is a side view showing dimensions A (total height), a2 (lead height), b (lead width), e (pitch), and e3 (total length). The top-right drawing is a perspective view showing dimensions L (lead length), G (lead width), C (lead thickness), c1 (lead angle), a1 (lead thickness), b1 (lead width), and E (package width). The bottom drawing is a top view showing dimensions D (total length), M (lead length), F (package width), and pin numbers 1, 7, 8, and 14.</p>						

4.3 TSSOP14 package mechanical data

Figure 2. TSSOP14 package

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

The figure includes three mechanical drawings of the TSSOP14 package. The top-left drawing is a side view showing dimensions A (total height), A1 (lead height), A2 (lead thickness), b (lead width), e (pitch), and c (lead thickness at the end). The top-right drawing is a cross-sectional view showing dimensions K (lead thickness), L (lead length), and E (package width). The bottom drawing is a top-down view showing dimensions D (package length) and E1 (package width), along with a PIN 1 IDENTIFICATION circle and the number 1.

5 Ordering information

Table 5. Order codes

Part number	Temperature range	Package	Packaging	Marking
TS3704CN	0°C, +70°C	DIP14	Tube	TS3704CN
TS3704CD/CDT		SO14	Tube or tape & reel	3704C
TS3704IN	-40°C, +125°C	DIP14	Tube	TS3704IN
TS3704ID/IDT		SO14	Tube or tape & reel	3704I
TS3704IPT		TSSOP14	Tape & reel	3704I
TS3704MN	-55°C, +125°C	DIP14	Tube	TS3704MN
TS3704MD/MDT		SO14	Tube or tape & reel	3704M
TS3704MPT		TSSOP14	Tape & reel	3704M

6 Revision history

Date	Revision	Changes
1-Oct-2004	1	Initial release.
1-Aug-2005	2	1 - PPAP references inserted in the datasheet. 2 - ESD protection inserted in Table 1 on page 3 .
26-Feb-2007	3	PPAP references removed. Updated footnotes related to ESD in Table 1 on page 3 . Added Table 2 on page 3 . Order codes added to Table 5 on page 10 .

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